

ABSTRACT

A plastic package for use in semiconductor devices, which has a plurality of metallic terminals exposed on a package surface and a metallic bump attached to each of
5 said terminals. The bumps are made of reflowable metal and have approximately uniform height. An adherent layer of polymer material covers the package surface and surrounds each of the bumps to form a solid meniscus. The layer has
10 a thickness between a quarter and one half of the bump height. An analogous methodology applies to plastic assembly boards.